



INA200 INA201 INA202 SBOS374C – NOVEMBER 2006 – REVISED OCTOBER 2010

High-Side Measurement Current-Shunt Monitor with Open-Drain Comparator and Reference

Check for Samples: INA200, INA201, INA202

FEATURES

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- COMPLETE CURRENT SENSE SOLUTION
- 0.6V INTERNAL VOLTAGE REFERENCE
- INTERNAL OPEN-DRAIN COMPARATOR
- LATCHING CAPABILITY ON COMPARATOR
- COMMON-MODE RANGE: -16V to +80V
- HIGH ACCURACY: 3.5% MAX ERROR OVER TEMPERATURE
- BANDWIDTH: 500kHz (INA200)
- QUIESCENT CURRENT: 1800μA (max)
- PACKAGES: SO-8, MSOP-8

APPLICATIONS

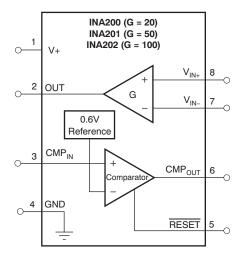
- NOTEBOOK COMPUTERS
- CELL PHONES
- TELECOM EQUIPMENT
- AUTOMOTIVE
- POWER MANAGEMENT
- BATTERY CHARGERS
- WELDING EQUIPMENT

DESCRIPTION

The INA200, INA201, and INA202 are high-side current-shunt monitors with voltage output. The INA200–INA202 can sense drops across shunts at common-mode voltages from -16V to 80V. The INA200–INA202 are available with three output voltage scales: 20V/V, 50V/V, and 100V/V, with up to 500kHz bandwidth.

The INA200, INA201, and INA202 also incorporate an open-drain comparator and internal reference providing a 0.6V threshold. External dividers are used to set the current trip point. The comparator includes a latching capability, which can be made transparent by grounding (or leaving open) the RESET pin.

The INA200, INA201, and INA202 operate from a single +2.7V to +18V supply, drawing a maximum of 1800μ A of supply current. Package options include the very small MSOP-8 and the SO-8. All versions are specified over the extended operating temperature range of -40° C to +125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PRODUCT	GAIN	PACKAGE-LEAD	PACKAGE DESIGNATOR	PACKAGE MARKING				
1014.000	201/11/	MSOP-8	DGK	BQH				
INA200	20V/V	SO-8	D	INA200A				
1014.004	50) (1) (MSOP-8	DGK	BQJ				
INA201	50V/V	SO-8	D	INA201A				
1014.202	100\/\/	MSOP-8		BQL				
INA202	100V/V	SO-8	D	INA202A				

ORDERING INFORMATION⁽¹⁾

(1) For the most current package and ordering information see the Package Option Addendum at the end of this document, or see the device product folder at www.ti.com.

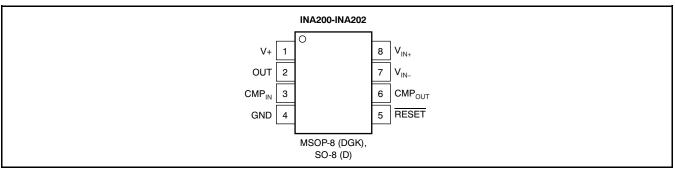
ABSOLUTE MAXIMUM RATINGS⁽¹⁾

		VALUE	UNIT
Sup	bly Voltage, V+	18	V
Curr	ent-Shunt Monitor Analog Inputs, V _{IN+} , V _{IN-}		
	Differential $(V_{IN+}) - (V_{IN-})$	-18 to +18	V
	Common Mode ⁽²⁾	-16 to +80	V
Com	parator Analog Input and Reset Pins ⁽²⁾	GND – 0.3 to (V+) + 0.3	V
Ana	og Output, Out ⁽²⁾	GND – 0.3 to (V+) + 0.3	V
Com	parator Output, Out Pin ⁽²⁾	GND – 0.3 to 18	V
Inpu	t Current Into Any Pin ⁽²⁾	5	mA
Ope	rating Temperature	-55 to +150	°C
Stor	age Temperature	-65 to +150	°C
Juno	tion Temperature	+150	°C
ES	Human Body Model (HBM)	4000	V
D Rat ing s	Charged Device Model (CDM)	1000	V

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not supported.

(2) This voltage may exceed the ratings shown if the current at that pin is limited to 5mA.

PIN CONFIGURATIONS





ELECTRICAL CHARACTERISTICS: CURRENT-SHUNT MONITOR

Boldface limits apply over the specified temperature range: $T_A = -40^{\circ}C$ to $+125^{\circ}C$. At $T_A = +25^{\circ}C$, $V_S = +12V$, $V_{CM} = +12V$, $V_{SENSE} = 100$ mV, $R_L = 10$ k Ω to GND, $R_{PULL-UP} = 5.1$ k Ω connected from CMP_{OUT} to V_S , and $CMP_{IN} = GND$, unless otherwise noted.

		INA200, INA201, INA202					
CURRENT-SHUNT MONITOR PAR	AMETERS	CONDITIONS	MIN	ТҮР	MAX	UNIT	
INPUT							
Full-Scale Sense Input Voltage	V _{SENSE}	$V_{SENSE} = V_{IN+} - V_{IN-}$		0.15	(V _S - 0.25)/Gain	V	
Common-Mode Input Range	V _{CM}		-16		80	v	
Common-Mode Rejection	CMR	$V_{IN+} = -16V$ to +80V	80	100		dB	
Over Temperature		V _{IN+} = +12V to +80V	100	123		dB	
Offset Voltage, RTI ⁽¹⁾	V _{OS}			±0.5	±2.5	mV	
+25°C to +125°C					±3	mV	
–40°C to +25°C					±3.5	mV	
vs Temperature	dV _{OS} /dT	T _{MIN} to T _{MAX}		5		μ ν/°C	
vs Power Supply	PSR	$V_{OUT} = 2V, V_{IN+} = +18V, 2.7V$		2.5	100	μ V/V	
Input Bias Current, V _{IN-} Pin	I _B			±9	±16	μΑ	
OUTPUT (V _{SENSE} ≥ 20mV)							
Gain:	G						
INA200				20		V/V	
INA201				50		V/V	
INA202				100		V/V	
Gain Error		V _{SENSE} = 20mV to 100mV		±0.2	±1	%	
Over Temperature		V _{SENSE} = 20mV to 100mV			±2	%	
Total Output Error ⁽²⁾		V_{SENSE} = 120mV, V_S = +16V		±0.75	±2.2	%	
Over Temperature		V_{SENSE} = 120mV, V_S = +16V			±3.5	%	
Nonlinearity Error ⁽³⁾		V _{SENSE} = 20mV to 100mV		±0.002		%	
Output Impedance	Ro			1.5		Ω	
Maximum Capacitive Load		No Sustained Oscillation		10		nF	
OUTPUT (V _{SENSE} < 20mV) ⁽⁴⁾							
INA200, INA201, INA202		$-16V \le V_{CM} < 0V$		300		mV	
INA200		$0V \le V_{CM} \le V_S, V_S = 5V$			0.4	V	
INA201		$0V \le V_{CM} \le V_S, V_S = 5V$			1	V	
INA202		$0V \le V_{CM} \le V_S, V_S = 5V$			2	V	
INA200, INA201, INA202		$V_{\rm S} < V_{\rm CM} \le 80V$		300		mV	
VOLTAGE OUTPUT ⁽⁵⁾							
Output Swing to the Positive Rail		$V_{IN-} = 11V, V_{IN+} = 12V$		(V+) – 0.15	(V+) – 0.25	v	
Output Swing to GND ⁽⁶⁾		$V_{IN-} = 0V, V_{IN+} = -0.5V$		(V _{GND}) + 0.004	(V _{GND}) + 0.05	v	
FREQUENCY RESPONSE							
Bandwidth:	BW						
INA200		$C_{LOAD} = 5pF$		500		kHz	
INA201		$C_{LOAD} = 5 pF$		300		kHz	
INA202		$C_{LOAD} = 5pF$		200		kHz	
Phase Margin		$C_{LOAD} < 10nF$		40		Degrees	
Slew Rate	SR			1		V/µs	
Settling Time (1%)		$V_{SENSE} = 10mV_{PP}$ to $100mV_{PP}$, $C_{LOAD} = 5pF$		2		μS	
NOISE, RTI							
Voltage Noise Density				40		nV/√Hz	

(1) Offset is extrapolated from measurements of the output at 20mV and 100mV V_{SENSE}.

Total output error includes effects of gain error and V_{OS} . (2)

(3) Linearity is best fit to a straight line.

(4) For details on this region of operation, see the Accuracy Variations section in the Applications Information.

See Typical Characteristic curve Output Swing vs Output Current. (5)

(6) Specified by design.

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INSTRUMENTS

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ELECTRICAL CHARACTERISTICS: COMPARATOR

Boldface limits apply over the specified temperature range: $T_A = -40^{\circ}C$ to $+125^{\circ}C$.

At $T_A = +25^{\circ}$ C, $V_S = +12$ V, $V_{CM} = +12$ V, $V_{SENSE} = 100$ mV, $R_L = 10$ k Ω to GND, and $R_{PULL-UP} = 5.1$ k Ω connected from CMP_{OUT} to V_S , unless otherwise noted.

			I	NA200, INA201, IN	A202	
COMPARATOR PARAMETERS		CONDITIONS	MIN	ТҮР	MAX	UNIT
OFFSET VOLTAGE						
Threshold		T _A = +25°C	590	608	620	mV
Over Temperature			586		625	mV
Hysteresis ⁽¹⁾		$T_A = -40^{\circ}C$ to $+85^{\circ}C$		8		mV
INPUT BIAS CURRENT ⁽²⁾						
CMP _{IN} Pin				0.005	10	nA
vs Temperature					15	nA
INPUT VOLTAGE RANGE						
CMP _{IN} Pin				0V to V _S – 1.5V		V
OUTPUT (OPEN-DRAIN)						
Large-Signal Differential Voltage Gain		CMP V _{OUT} 1V to 4V, R _L ≥ 15k Ω Connected to 5V		200		V/mV
High-Level Leakage Current ^{(3) (4)}	I _{LKG}	$V_{ID} = 0.4V, V_{OH} = V_S$		0.0001	1	μΑ
Low-Level Output Voltage ⁽³⁾	V _{OL}	$V_{ID} = -0.6V, I_{OL} = 2.35mA$		220	300	mV
RESPONSE TIME						
Response Time ⁽⁵⁾		R_L to 5V, C_L = 15pF, 100mV Input Step with 5mV Overdrive		1.3		μS
RESET						
RESET Threshold ⁽⁶⁾				1.1		V
Logic Input Impedance				2		MΩ
Minimum RESET Pulse Width				1.5		μS
RESET Propagation Delay				3		μS

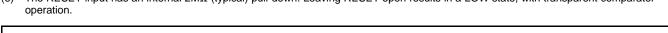
(1) Hysteresis refers to the threshold (the threshold specification applies to a rising edge of a noninverting input) of a falling edge on the noninverting input of the comparator; refer to Figure 1.

(2) Specified by design.

(3) V_{ID} refers to the differential voltage at the comparator inputs.

(4) Open-drain output can be pulled to the range of +2.7V to +18V, regardless of V_{S} .

(5) The comparator response time specified is the interval between the input step function and the instant when the output crosses 1.4V. (6) The RESET input has an internal $2M\Omega$ (typical) pull-down. Leaving RESET open results in a LOW state, with transparent comparator



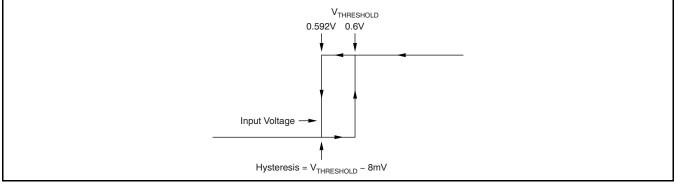


Figure 1. Typical Comparator Hysteresis

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ELECTRICAL CHARACTERISTICS: GENERAL

Boldface limits apply over the specified temperature range: $T_A = -40^{\circ}C$ to $+125^{\circ}C$.

At $T_A = +25^{\circ}$ C, $V_S = +12$ V, $V_{CM} = +12$ V, $V_{SENSE} = 100$ mV, $R_L = 10$ k Ω to GND, $R_{PULL-UP} = 5.1$ k Ω connected from CMP_{OUT} to V_S , and CMP_{IN} = 1V, unless otherwise noted.

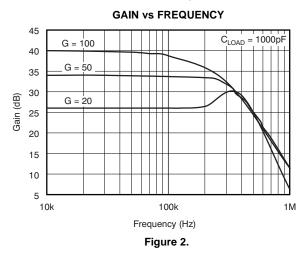
		IN/	200, INA201, IN	IA202	
GENERAL PARAMETERS	CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLY					
Operating Power Supply V _S		+2.7		+18	v
Quiescent Current I _Q	$V_{OUT} = 2V$		1350	1800	μA
Over Temperature	V _{SENSE} = 0mV			1850	μΑ
Comparator Power-On Reset Threshold ⁽¹⁾			1.5		V
TEMPERATURE					
Specified Temperature Range		-40		+125	°C
Operating Temperature Range		-55		+150	°C
Storage Temperature Range		-65		+150	°C
Thermal Resistance θ_{JA}					
MSOP-8 Surface-Mount			200		°C/W
SO-8			150		°C/W

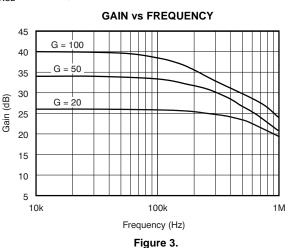
(1) The INA200, INA201, and INA202 are designed to power-up with the comparator in a defined reset state as long as RESET is open or grounded. The comparator is in reset as long as the power supply is below the voltage shown here. The comparator assumes a state based on the comparator input above this supply voltage. If RESET is high at power-up, the comparator output comes up high and requires a reset to assume a low state, if appropriate.



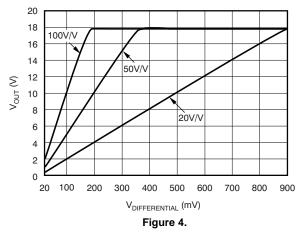


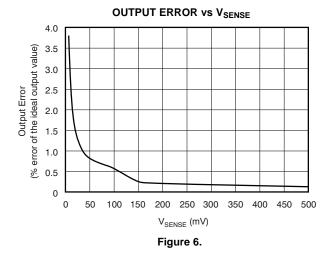
At $T_A = +25^{\circ}C$, $V_S = +12V$, $V_{IN+} = 12V$, and $V_{SENSE} = 100mV$, unless otherwise noted.



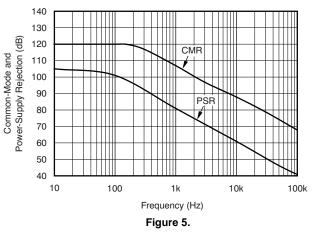


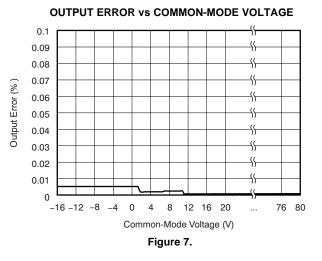
GAIN PLOT





COMMON-MODE AND POWER-SUPPLY REJECTION vs FREQUENCY





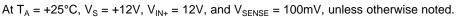
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TYPICAL CHARACTERISTICS (continued)



POSITIVE OUTPUT VOLTAGE SWING vs OUTPUT CURRENT $\frac{12}{V_s = 12V}$ 3.5 3.0

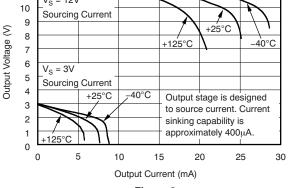


Figure 8.

QUIESCENT CURRENT vs COMMON-MODE VOLTAGE

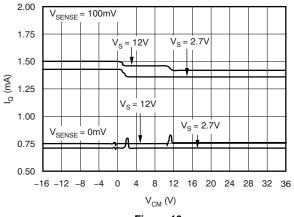
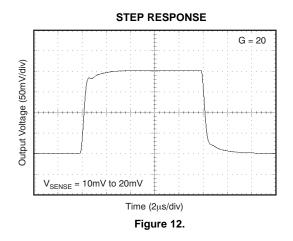


Figure 10.





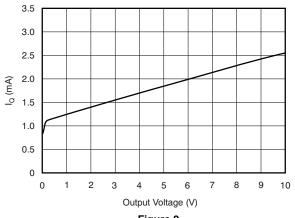
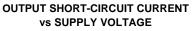
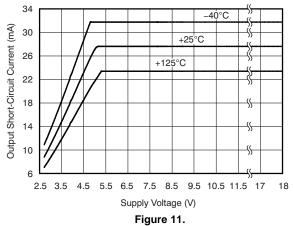
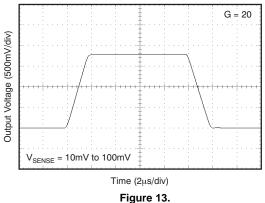


Figure 9.





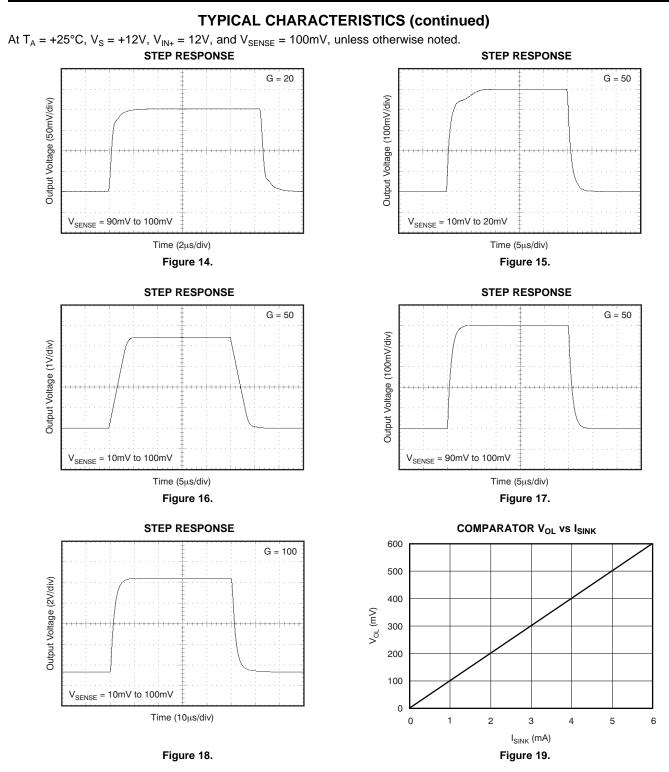




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TEXAS INSTRUMENTS

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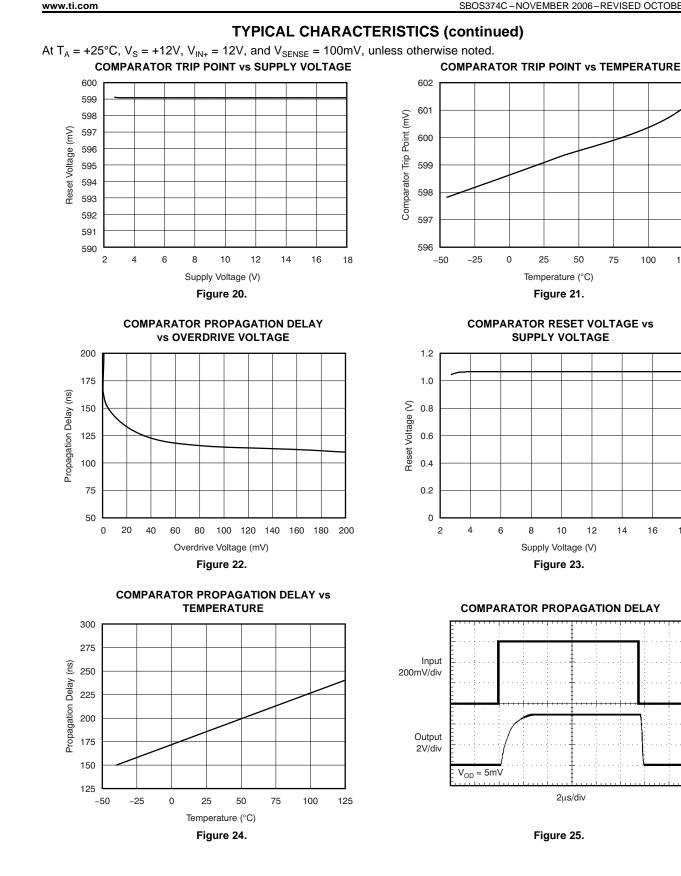
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100

16

18

125



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APPLICATIONS INFORMATION

BASIC CONNECTIONS

Figure 26 shows the basic connections of the INA200, INA201, and INA202. The input pins, V_{IN+} and V_{IN-} , should be connected as closely as possible to the shunt resistor to minimize any resistance in series with the shunt resistance.

Power-supply bypass capacitors are required for stability. Applications with noisy or high-impedance power supplies may require additional decoupling capacitors to reject power-supply noise. Connect bypass capacitors close to the device pins.

POWER SUPPLY

The input circuitry of the INA200, INA201, and INA202 can accurately measure beyond the power-supply voltage, V+. For example, the V+ power supply can be 5V, whereas the load power-supply voltage is up to +80V. The output voltage range of the OUT terminal, however, is limited by the voltages on the power-supply pin.

ACCURACY VARIATIONS AS A RESULT OF $V_{\mbox{sense}}$ AND COMMON-MODE VOLTAGE

The accuracy of the INA200, INA201, and INA202 current shunt monitors is a function of two main variables: V_{SENSE} ($V_{IN+} - V_{IN-}$) and common-mode voltage, V_{CM} , relative to the supply voltage, V_S . V_{CM} is expressed as ($V_{IN+} + V_{IN-}$)/2; however, in practice, V_{CM} is seen as the voltage at V_{IN+} because the voltage drop across V_{SENSE} is usually small.

This section addresses the accuracy of these specific operating regions:

- Normal Case 1: V_{SENSE} ≥ 20mV, V_{CM} ≥ V_S
- Normal Case 2: V_{SENSE} ≥ 20mV, V_{CM} < V_S
- Low V_{SENSE} Case 1: V_{SENSE} < 20mV, -16V \leq V_{CM} < 0
- Low V_{SENSE} Case 2: V_{SENSE} < 20mV, 0V \leq V_{CM} \leq V_S
- Low V_{SENSE} Case 3: V_{SENSE} < 20mV, V_S < V_{CM} \le 80V

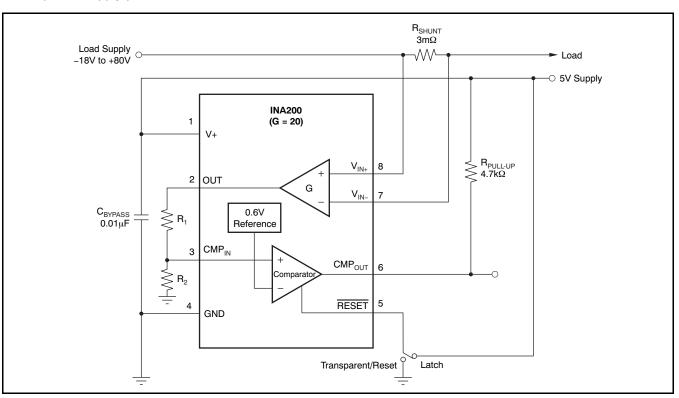


Figure 26. INA200 Basic Connections



Normal Case 1: $V_{SENSE} \ge 20mV$, $V_{CM} \ge V_{S}$

This region of operation provides the highest accuracy. Here, the input offset voltage is characterized and measured using a two-step method. First, the gain is determined by Equation 1.

$$G = \frac{V_{OUT1} - V_{OUT2}}{100mV - 20mV}$$
(1)

where:

 V_{OUT1} = Output Voltage with V_{SENSE} = 100mV

 V_{OUT2} = Output Voltage with V_{SENSE} = 20mV

Then the offset voltage is measured at V_{SENSE} = 100mV and referred to the input (RTI) of the current shunt monitor, as shown in Equation 2.

$$V_{OS}RTI (Referred-To-Input) = \left[\frac{V_{OUT1}}{G}\right] - 100mV$$
 (2)

In the Typical Characteristics, the *Output Error vs Common-Mode Voltage* curve (Figure 7) shows the highest accuracy for the this region of operation. In this plot, $V_S = 12V$; for $V_{CM} \ge 12V$, the output error is at its minimum. This case is also used to create the $V_{SENSE} \ge 20$ mV output specifications in the Electrical Characteristics table.

Normal Case 2: V_{SENSE} ≥ 20mV, V_{CM} < V_S

This region of operation has slightly less accuracy than Normal Case 1 as a result of the common-mode operating area in which the part functions, as seen in the *Output Error vs Common-Mode Voltage* curve (Figure 7). As noted, for this graph $V_S = 12V$; for $V_{CM} < 12V$, the Output Error increases as V_{CM} becomes less than 12V, with a typical maximum error of 0.005% at the most negative $V_{CM} = -16V$.

Low V_{SENSE} Case 1: $V_{SENSE} < 20mV$, –16V $\leq V_{CM} < 0$; and Low V_{SENSE} Case 3: $V_{SENSE} < 20mV$, $V_S < V_{CM} \leq 80V$

Although the INA200 family of devices are not designed for accurate operation in either of these regions, some applications are exposed to these conditions. For example, when monitoring power supplies that are switched on and off while V_S is still applied to the INA200, INA201, or INA202, it is important to know what the behavior of the devices will be in these regions.

As V_{SENSE} approaches 0mV, in these V_{CM} regions, the device output accuracy degrades. A

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larger-than-normal offset can appear at the current shunt monitor output with a typical maximum value of $V_{OUT} = 300 \text{mV}$ for $V_{SENSE} = 0 \text{mV}$. As V_{SENSE} approaches 20 mV, V_{OUT} returns to the expected output value with accuracy as specified in the Electrical Characteristics. Figure 27 illustrates this effect using the INA202 (Gain = 100).

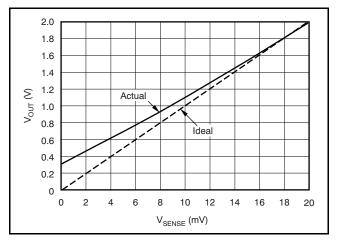


Figure 27. Example for Low V_{SENSE} Cases 1 and 3 (INA202, Gain = 100)

Low V_{SENSE} Case 2: V_{SENSE} < 20mV, $0V \le V_{CM} \le V_S$

This region of operation is the least accurate for the INA200 family. To achieve the wide input common-mode voltage range, these devices use two op amp front ends in parallel. One op amp front end operates in the positive input common-mode voltage range, and the other in the negative input region. For this case, neither of these two internal amplifiers dominates and overall loop gain is very low. Within this region, V_{OUT} approaches voltages close to linear operation levels for Normal Case 2. This deviation from linear operation becomes greatest the closer V_{SENSE} approaches 0V. Within this region, as V_{SENSE} approaches 20mV, device operation is closer to that described by Normal Case 2. Figure 28 illustrates this behavior for the INA202. The VOLT maximum peak for this case is tested by maintaining a constant V_{S} , setting $V_{SENSE} = 0mV$ and sweeping V_{CM} from 0V to V_{S} . The exact V_{CM} at which V_{OUT} peaks during this test varies from part to part, but the VOUT maximum peak is tested to be less than the specified $V_{\mbox{\scriptsize OUT}}$ tested limit.

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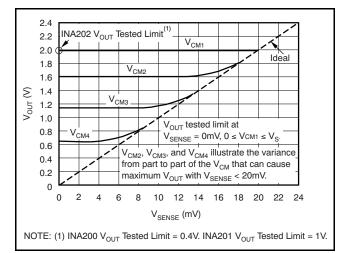


Figure 28. Example for Low V_{SENSE} Case 2 (INA202, Gain = 100)

SELECTING R_s

The value chosen for the shunt resistor, R_S , depends on the application and is a compromise between small-signal accuracy and maximum permissible voltage loss in the measurement line. High values of R_S provide better accuracy at lower currents by minimizing the effects of offset, while low values of R_S minimize voltage loss in the supply line. For most applications, best performance is attained with an R_S value that provides a full-scale shunt voltage range of 50mV to 100mV. Maximum input voltage for accurate measurements is 500mV.

TRANSIENT PROTECTION

The -16V to +80V common-mode range of the INA200, INA201, and INA202 is ideal for withstanding automotive fault conditions ranging from 12V battery reversal up to +80V transients, since no additional protective components are needed up to those levels. In the event that the INA200, INA201, and INA202 are exposed to transients on the inputs in excess of their ratings, then external transient absorption with semiconductor transient absorbers (such as zeners) will be necessary. Use of MOVs or VDRs is not recommended except when they are used in addition to a semiconductor transient absorber. Select the transient absorber such that it will never allow the INA200, INA201, and INA202 to be exposed to transients greater than +80V (that is, allow for transient absorber tolerance, as well as additional voltage due to transient absorber dynamic impedance). Despite the use of internal zener-type ESD protection, the INA200, INA201, and INA202 do not lend themselves to using external resistors in series with the inputs since the internal gain resistors can vary up to $\pm 30\%$. (If gain accuracy is not important, then resistors can be added in series with the INA200, INA201, and INA202 inputs with two equal resistors on each input.)

OUTPUT VOLTAGE RANGE

The output of the INA200, INA201, and INA202 is accurate within the output voltage swing range set by the power supply pin, V+. This performance is best illustrated when using the INA202 (a gain of 100 version), where a 100mV full-scale input from the shunt resistor requires an output voltage swing of +10V, and a power-supply voltage sufficient to achieve +10V on the output.

INPUT FILTERING

An obvious and straightforward location for filtering is at the output of the INA200, INA201, and INA202 series; however, this location negates the advantage of the low output impedance of the internal buffer. The only other option for filtering is at the input pins of the INA200, INA201, and INA202, which is complicated by the internal $5k\Omega + 30\%$ input impedance; this is illustrated in Figure 29. Using the lowest possible resistor values minimizes both the initial shift in gain and effects of tolerance. The effect on initial gain is given by Equation 3:

Gain Error % = 100 -
$$\left[100 \times \frac{5k\Omega}{5k\Omega + R_{FILT}}\right]$$
 (3)

Total effect on gain error can be calculated by replacing the $5k\Omega$ term with $5k\Omega - 30\%$, (or $3.5k\Omega$) or $5k\Omega + 30\%$ (or $6.5k\Omega$). The tolerance extremes of R_{FILT} can also be inserted into the equation. If a pair of $100\Omega \ 1\%$ resistors are used on the inputs, the initial gain error will be 1.96%. Worst-case tolerance conditions will always occur at the lower excursion of the internal $5k\Omega$ resistor ($3.5k\Omega$), and the higher excursion of $R_{FILT} - 3\%$ in this case.

Note that the specified accuracy of the INA200, INA201, and INA202 must then be combined in addition to these tolerances. While this discussion treated accuracy worst-case conditions by combining the extremes of the resistor values, it is appropriate to use geometric mean or root sum square calculations to total the effects of accuracy variations.

COMPARATOR

The INA200, INA201, and INA202 devices incorporate an open-drain comparator. This comparator typically has 2mV of offset and a 1.3μ s (typical) response time. The output of the comparator latches and is reset through the RESET pin; see Figure 30.

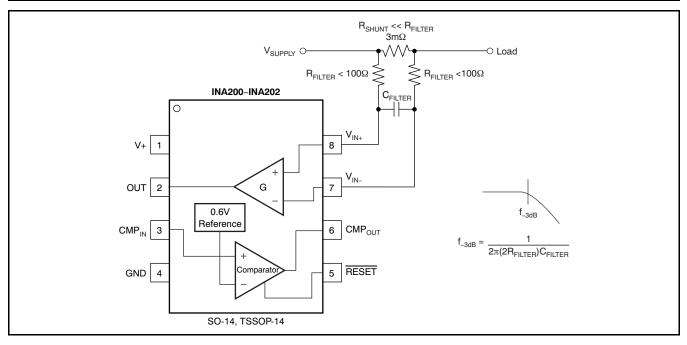
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INA202 SBOS374C-NOVEMBER 2006-REVISED OCTOBER 2010

INA200

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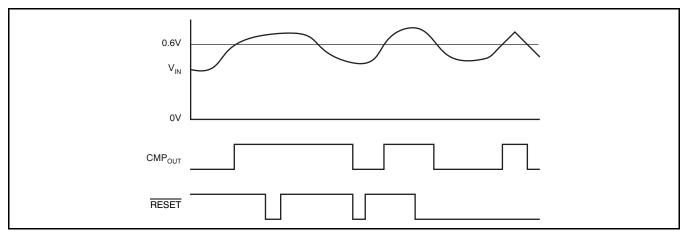


Figure 30. Comparator Latching Capability

INA200 INA201 INA202



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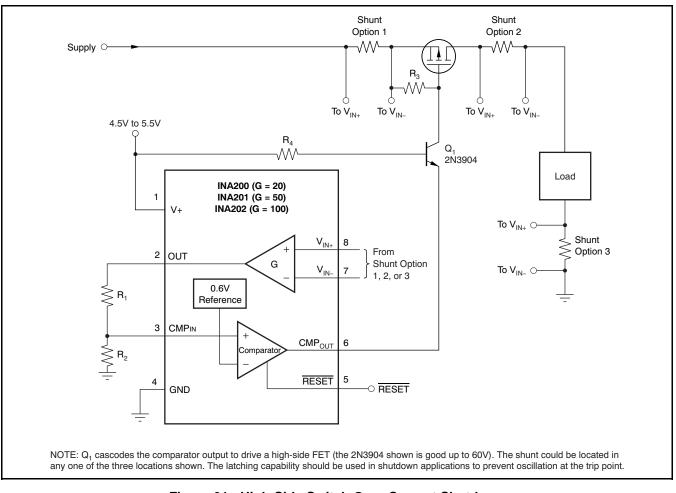


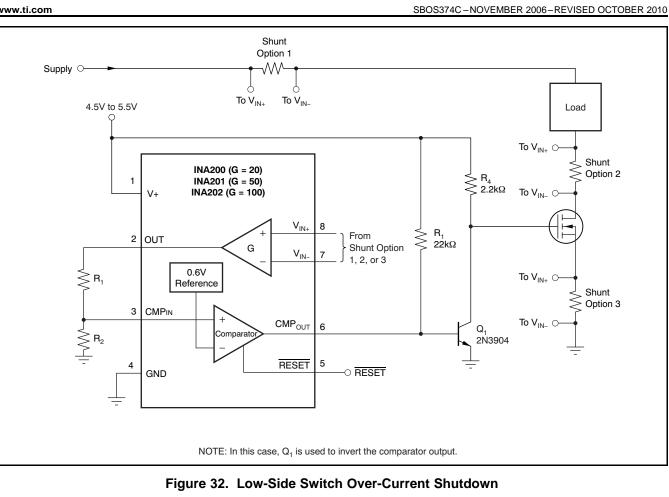
Figure 31. High-Side Switch Over-Current Shutdown



INA201 **INA202**

INA200

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INA200 INA201 INA202



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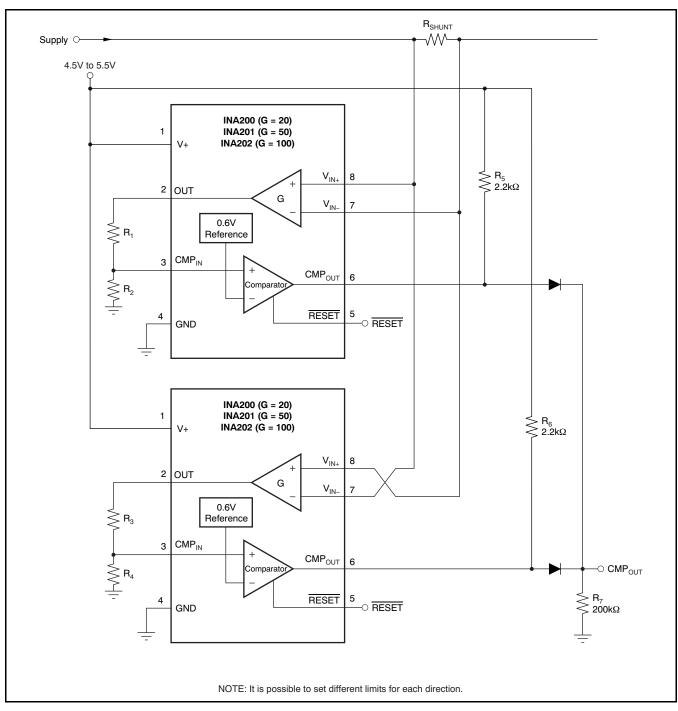


Figure 33. Bidirectional Over-Current Comparator



REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

CI	hanges from Revision B (October, 2007) to Revision C Pa	age
•	Changed title of data sheet	1
•	Updated document format to current standards	1
•	Revised front-page figure	1



9-Aug-2011

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
INA200AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA200AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA200AIDGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAC	GLevel-2-260C-1 YEAR	
INA200AIDGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAC	GLevel-2-260C-1 YEAR	
INA200AIDGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAC	GLevel-2-260C-1 YEAR	
INA200AIDGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAC	GLevel-2-260C-1 YEAR	
INA200AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA200AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA201AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA201AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA201AIDGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA201AIDGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA201AIDGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA201AIDGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA201AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA201AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA202AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	



Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
INA202AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA202AIDGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA202AIDGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA202AIDGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA202AIDGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA202AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
INA202AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF INA201 :

• Automotive: INA201-Q1

NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

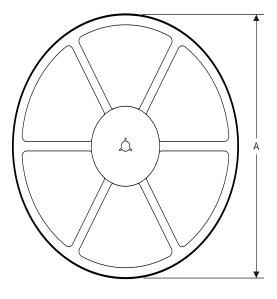
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS INSTRUMENTS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA200AIDGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
INA200AIDGKT	MSOP	DGK	8	250	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
INA200AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
INA201AIDGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
INA201AIDGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
INA201AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
INA202AIDGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
INA202AIDGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
INA202AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA200AIDGKR	MSOP	DGK	8	2500	366.0	364.0	50.0
INA200AIDGKT	MSOP	DGK	8	250	366.0	364.0	50.0
INA200AIDR	SOIC	D	8	2500	367.0	367.0	35.0
INA201AIDGKR	MSOP	DGK	8	2500	367.0	367.0	35.0
INA201AIDGKT	MSOP	DGK	8	250	210.0	185.0	35.0
INA201AIDR	SOIC	D	8	2500	367.0	367.0	35.0
INA202AIDGKR	MSOP	DGK	8	2500	367.0	367.0	35.0
INA202AIDGKT	MSOP	DGK	8	250	210.0	185.0	35.0
INA202AIDR	SOIC	D	8	2500	367.0	367.0	35.0

DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.

- D Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



LAND PATTERN DATA



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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